
MULTILAYER NICKEL PLATING PROCESSES

- SEMIGLANZ 854** Semi bright nickel plating process for the deposition of thick, levelled and very ductile layers. Provide lowest electro-negative potential for use in duplex nickel system.
- SEMIGLANZ HSA** High sulphur additive for multilayer triplex nickel plating.
- MICROPOR 855** A nickel process to produce induced microporosity in subsequent hexavalent chromium deposits
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